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**IGBT** 

# FGS15N40L

## **General Description**

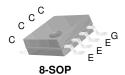
Insulated Gate Bipolar Transistors(IGBTs) with trench gate structure have superior performance in conductance and switching to planar gate structure and also have wide noise immunity. These devices are well suitable for strobe application

### **Features**

- High Input Impedance
- High Peak Current Capability (130A)
- · Easy Gate Drive

# **Application**

Strobe Flash





# **Absolute Maximum Ratings**

T<sub>C</sub> = 25°C unless otherrwise noted

Symbol	Description		FGS15N40L	Units
V <sub>CES</sub>	Collector-Emitter Voltage		400	V
V <sub>GES</sub>	Gate-Emitter Voltage		± 6	V
I <sub>CM (1)</sub>	Pulsed Collector Current		130	Α
P <sub>C</sub>	Maximum Power Dissipation	@ T <sub>a</sub> = 25°C	2.0	W
TJ	Operating Junction Temperature		-40 to +150	°C
T <sub>stg</sub>	Storage Temperature Range		-40 to +150	°C
TL	Maximum Lead Temp. for soldering PurPoses from case for 5 secnds		300	°C

Notes:
(1) Repetitive rating: Pulse width limited by max. junction temperature

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient(PCB Mount)		62.5	°C/W

Notes: Mounted on 1" square PCB(FR4 or G-10 Material)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V$ , $I_C = 1mA$	450			V
I <sub>CES</sub>	Collector Cut-off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			10	μΑ
I <sub>GES</sub>	G-E leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 0.1	μΑ
On Characteristics						
$V_{GE(th)}$	G-E threshold Voltage	$I_C = 0V$ , $I_C = 1mA$	-	-	1.4	V
V <sub>CE(sat)</sub>	C-E Saturation Voltage	$I_C = 130A , V_{GE} = 4.0V$	2.0	4.5	8.0	V
D						
	c Characteristics					
C <sub>ies</sub>	c Characteristics Input Capacitance	V0V V30V		3800		pF
C <sub>ies</sub>	T	V <sub>GE</sub> = 0V , V <sub>CE</sub> = 30V		3800 45		pF pF
C <sub>ies</sub>	Input Capacitance	V <sub>GE</sub> = 0V , V <sub>CE</sub> = 30V f = 1MHz				
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	Input Capacitance Output Capacitance	GE . GE		45		pF
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub> Switching	Input Capacitance Output Capacitance Reverse Transfer Capacitance	f = 1MHz		45		pF
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub> Switching	Input Capacitance Output Capacitance Reverse Transfer Capacitance  ng Characteristics	f = 1MHz  V <sub>CC</sub> = 300V , I <sub>C</sub> = 130A		45 30		pF pF
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance  ng Characteristics Turn-On Delay Time	f = 1MHz		45 30 0.15	    0.3	pF pF

Notes : Recommendation of Rg Value : Rg  $\geq 15 \Omega$ 

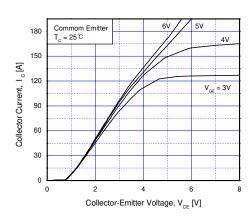


Fig 1. Typical Output Chacracteristics

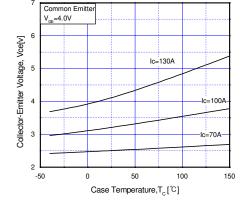


Fig 2. Saturation Voltage vs. Case Temerature at Variant Current Level

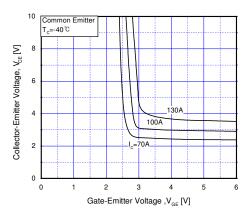


Fig 3. Saturation Voltage vs. V<sub>GE</sub>

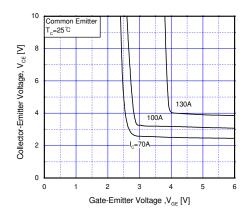


Fig 4. Saturation Voltage vs.  $V_{\text{GE}}$ 

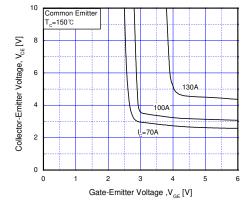


Fig 5. Saturation Voltage vs. V<sub>GE</sub>

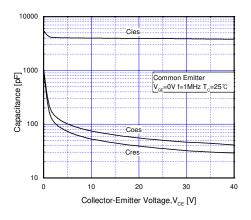


Fig 6. Capacitance Characteristics

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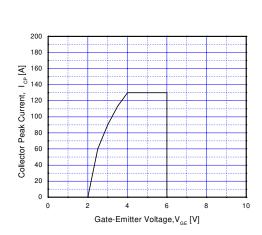
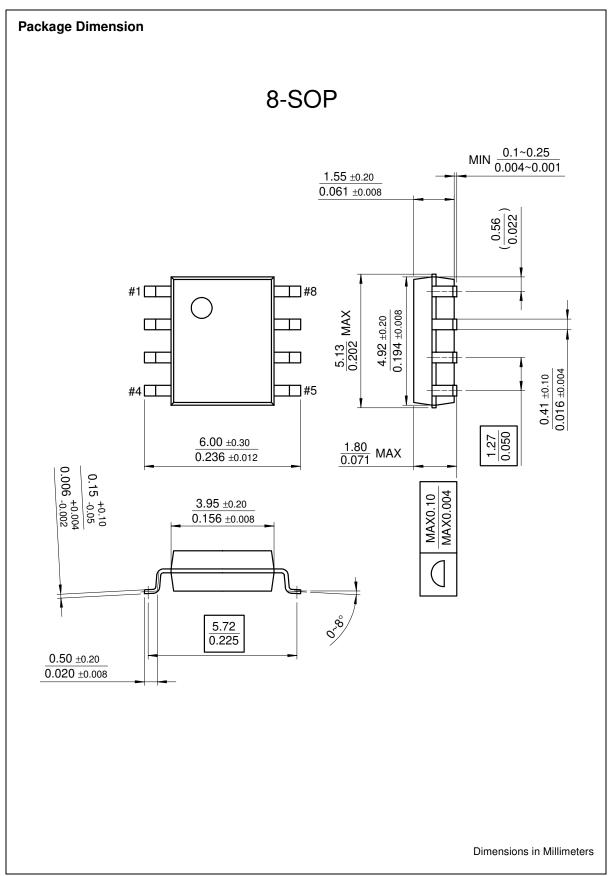


Fig 7. Collector Current Limit Vs Gate - Emitter Voltage Limit



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